



CLEAN VERSION OF AMENDED SPECIFICATION PARAGRAPHS

A SOLVENT PREWET AND METHOD TO DISPENSE THE SOLVENT PREWET

Applicant: John Whitman
Serial No.: 09/941,476

The paragraph beginning at page 2, line 20:

After several preliminary preparation steps, a wafer is ready to be coated with photoresist.

The goal of the coating step is to produce a uniform, adherent, defect-free polymeric film of desired thickness over the entire wafer. Spin coating is by far the most widely used technique to apply such films. This procedure is carried out by dispensing the resist solution onto the wafer surface, and then rapidly spinning the wafer until the resist is essentially dry. In order to maintain reproducible line width in VLSI fabrication applications, resist film uniformity across the wafer (and from wafer to wafer) should be within +/- 100 angstroms.